毫欧 毫欧电阻 毫欧制造	HoLR2512D封体合金系列规格书	系列号	HoLR
		修订日期	2020-7-15
		版本号	Ho-A1

Ӥ Specification

HoLR2512D

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■ ᵒᵒ پں Features：

合金芯片，封体工艺，焊接性能良好

高可靠性，高过载能力，产品精度高。

使用温度范围较宽无感型设计

电阻温度系数 TCR×10-6/℃≤25-50ppm

符合 ROHS 要求和无卤要求

■ 产品名称 Product Name

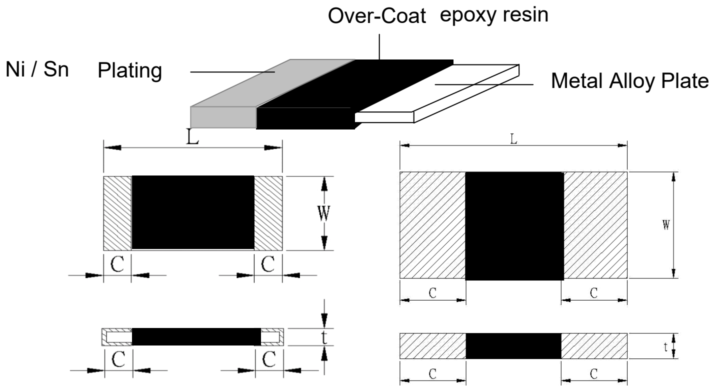
封体合金电阻

■ 产品型号 Product number

Ho	LR	2512D	3W	3mR	1%
制造商	产品系列	封装	额定功率	阻值	精度
Ho 毫欧电子	LR 合金	2512D	3．5W	0．25~1mR	±0．5% ±1% ±5%
			2W、3W	0．25~62mR	

国家高新技术企业 IATF16949 ISO9001 TÜV SÜD SGS

■ 产品结构及尺寸 Product structure and size



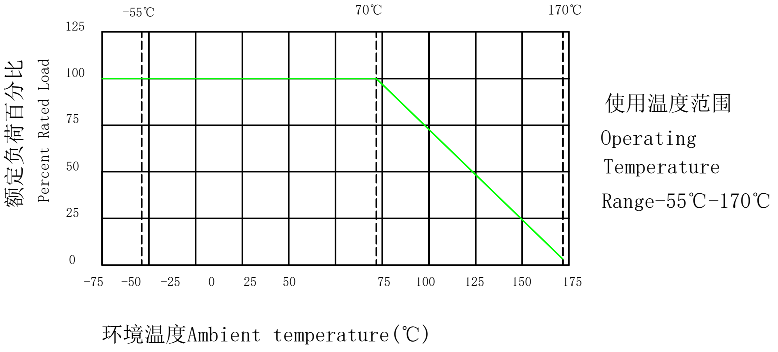
型号	功率	阻值	尺寸（mm）			
			L	W	C	T
HoLR2512D	3.5W	0.25mR~1mR	6.4±0.25	3.2±0.25	2.2±0.25	0.8±0.25
	2W、3W	0.25mR、0.5mR			1.72±0.25	
		1mR~4mR			1.5±0.25	
		5mR~62mR			0.85±0.25	

■ 电气参数 Electrical parameter

额定功率 Rated power	2W、3W、3.5W
阻值范围 Resistance range	0.25mR~62mR
最大额定电流 Max.Rated Current	6.32A~118.32A
准确度等级 AccuracyClass	0.5%、1%、5%
电阻温度系数 T.C.R (ppm / ℃)	≤25-50
工作温度范围 Operating Temperature Range	-55℃~+170℃

■ 功率曲线 Power curve

操作温度范围 - 55 ～+170 ℃电阻温度达到 70℃时降功率示意图

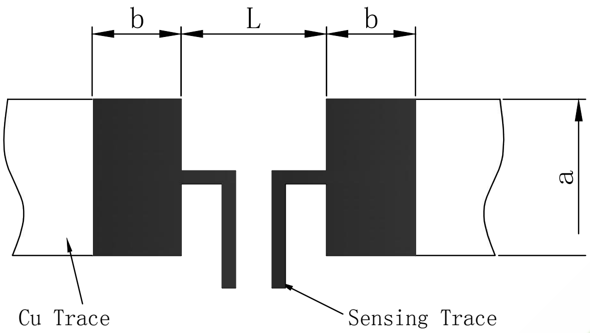


■ 额定电流计算公式 The rated current is calculated by the following Formu

I :Rated Current (A)
P:Rated Power (W)
R:Resistance Value (Ω)

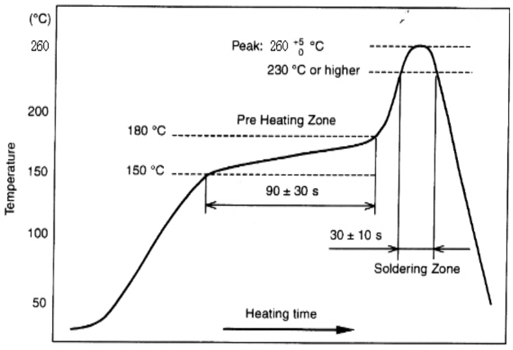
$$I = \sqrt{P/R}$$

■ 建议焊盘尺寸 Recommended Solder Pad Dimension

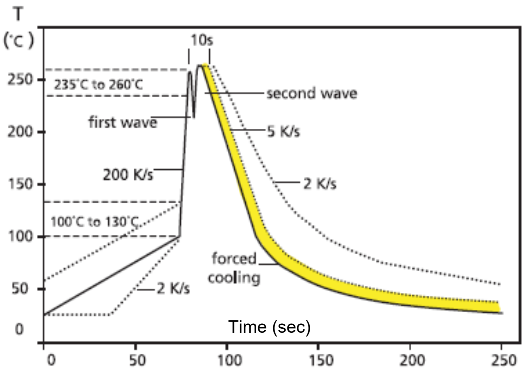


型号	阻值	尺寸（mm）		
		a	b	L
2512D	0.25~1	4.0	3.15	1.15
	0.25~0.5		2.57	2.11
	1~4		2.35	2.55
	5~62		1.70	3.85

■ 建议焊接参数 / Recommended Customer Soldering Parameters

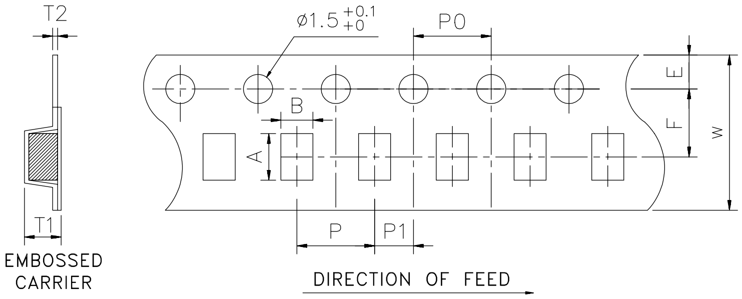


回流焊曲线图



波峰焊曲线图

■ 彩带尺寸 **Ribbon size**(Unit:mm)

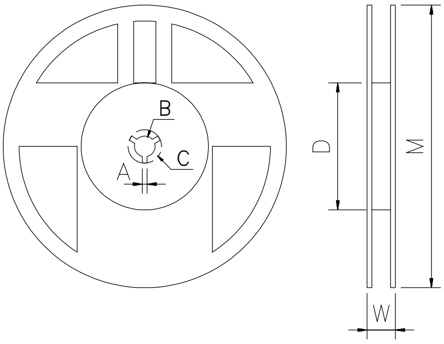


A	B	W	F	E	T1	T2	P	P0	P1
6.9±0.2	3.6±0.2	12±0.2	5.5±0.1	1.75±0.1	1.08±0.1	0.24±0.1	4±0.1	4±0.1	2.0± 0.10

■ 可靠性测试 **Reliability Tests**

Test Items	Reference standard	Condition of Test	Test Limits
Temperature Coefficient of Resistance	IEC60115-1 4.8 JIS C 5201-1 4.8	+25℃ ~ +125℃	Refer 4.0
Load Life	IEC60115-1 4.25.1 JIS C 5201-1 4.25.1	1000hours at rated power, 70℃, 1.5hours “ON”, 0.5hour “OFF”	< ±1%
Short Time Overload	IEC60115-1 4.13 JIS C 5201-1 4.13	5 X rated power for 5s	< ±0.5%
Moisture no Load	IEC60115-1 4.24.2.1a) JIS C 5201-1 4.24.2.1a)	85℃, 85%RH, 1000hrs	< ±1%
Temperature cycle	IEC60115-1 4.19 JIS C 5201-1 4.19	-55℃ & +155℃, 300cycle, 15min per extreme condition	< ±0.5%
Resistance to Soldering Heat	IEC60115-1 4.18 JIS C 5201-1 4.18	260±5℃ for20±1 sec	< ±0.5%
Solderability	IEC60115-1 4.17 JIS C 5201-1 4.17	245±5℃, 2±0.5sec	At least 95% of surface area of electrode shall be covered with new solder
High Temperature Exposure	IEC60115-1 4.23.2 JIS C 5201-1 4.23.2	170℃, 1000hrs	< ±1%
Low Temperature Storage	EC60115-1 4.23.4 JIS C 5201-1 4.23.4	-55℃, 1000hrs	<±0.5%
Substrate Bending	IEC60115-1 4.33 JIS C 5201-1 4.33	Bending width 2mm	< ±1%
Insulation Resistance	IEC60115-1 4.6 JIS C 5201-1 4.6	100V DC for 1 minute	>100 MΩ

■ 卷轴规格 Reel Specification



A	B	C	W	D	M
2.5±1	13.5±1	17.7±1	16.2±0.5	60±2	178±1

■ 包装方式 Packing

编带盘装：4000PCS/盘

修改履历表：

序号	修改内容	修改日期	修改原因
1	焊盘尺寸更新	2020-12-23	产品升级